

D3D7 FDH6626B



COLOR BAND DENOTES CATHODE

Small Signal Diode

Absolute Maximum Ratings * T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V_{RRM}	Maximum Repetitive Reverse Voltage	75	V	
I _{F(AV)}	Average Rectified Forward Current	200	mA	
I _{FSM}	Non-repetitive Peak Forward Surge Current			
	Pulse Width = 1.0 second	1.0	Α	
	Pulse Width = 1.0 microsecond	4.0	Α	
T _{STG}	Storage Temperature Range	-65 to +200	°C	
 Г _Ј	Operating Junction Temperature	175	°C	

^{*} These ratings are limiting values above which the serviceability of the diode may be impaired.

Thermal Characteristics

Symbol	Parameter	Min.	Max.	Units
P _D	Power Dissipation		500	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		300	°C/W

Electrical Characteristics T_A=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V _R	Breakdown Voltage	$I_{R} = 5.0 \mu A$	75		V
V _F	Forward Voltage	I _F = 1mA I _F = 100mA	550	1.1	mV V
I _R	Reverse Leakage	V _R = 50V V _R = 75V		50 5.0	nA μA
C _T	Total Capacitance	V _R = 0, f = 1.0MHz		2.5	pF
Q _S	Storage Charge	$I_F = 10\text{mA}, V_R = 6.0\text{V (600mA)}$ $I_F = 10\text{mA}, R_L = 100\Omega$		50	pC

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NOTES:

1) These ratings are based on a maximum junction temperature of 200 degrees C.

2) These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Typical Characteristics

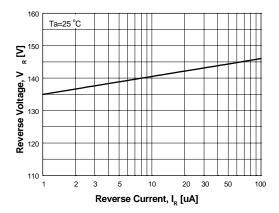


Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to $100\mu A$

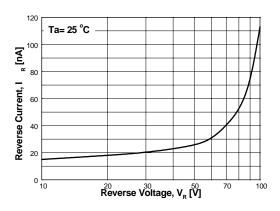


Figure 2. Reverse Current vs Reverse Voltage $\rm I_R$ - 10 to 100V

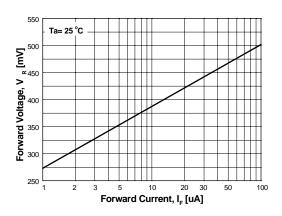


Figure 3. Forward Voltage vs Forward Current VF - 1 to $100\mu A$

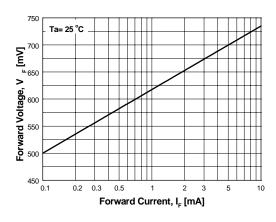


Figure 4. Forward Voltage vs Forward Current VF - 0.1 to 100mA

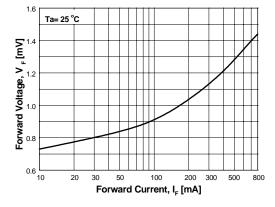


Figure 5. Forward Voltage vs Forward Current VF - 10 to 800mA

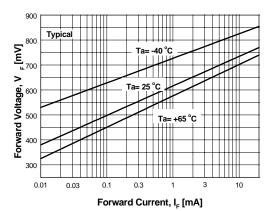


Figure 6. Forward Voltage vs Ambient Temperature VF - 0.01 - 20mA(-40 to +65 Deg C)

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Typical Characteristics (Continued)

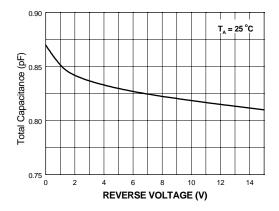


Figure 7. Total Capacitance

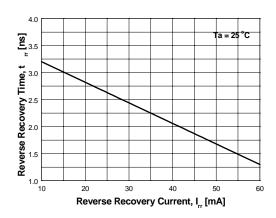


Figure 8. Reverse Recovery Time vs Reverse Recovery Current

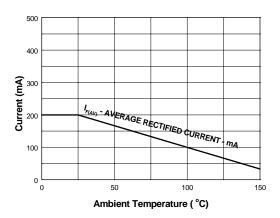


Figure 9. Average Rectified Current($I_{F(AV)}$) versus Ambient Temperature(T_A)

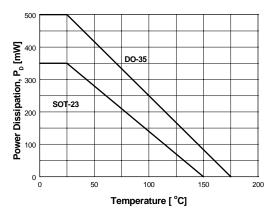


Figure 10. Power Derating Curve

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